

SUNEAST

SMT Electronic Assembly Equipment

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Series: Reflow Oven Series

Name: Reflow Oven: IPC-810

Model:

Features:

IPC-8 (Intelligent process control) series reflow oven, based on design of Genesis8 series, adopts advanced technology and inspection standard of IPC-985X (evaluating of reflow oven) , which fully satisfy the temperature profile requirement of IPC-7530 (Guidelines for Temperature Profiling for Mass Soldering Processes) and IPC/JEDEC J-STD-020C (Moisture/Reflow Sensitivity Classification for Nonhermetic



Series: Reflow Oven Series

Name: Genesis Lead Free Hot Air Reflow System Genesis6

Model:

Features:

1. Heating system: forced Convection Hot Air system, design of front and rear air flow circulation to effectively avoid mutual airflow influence between temperature zones, so as to ensure heating evenly and effectively. Temperature accuracy $\pm 1^{\circ}\text{C}$, heat up time ≤ 20 mins. Long life hot-air motor, adjustable wind speed and frequency



Series: Lead-Free Wave Soldering System

Name: Peak 2010

Model:

Features:

Peak series wave soldering, adopting design of digital, module, and human-oriented, shows superiority in function, performance, stability, reliability, safety, maintainability, operability and humanization, which not only reduces customers operation cost, and also provides customers' production an effective guarantee in quality and quantity. It is the "Peak work" of wave soldering industry and the preferred brand product for



Series: Lead-Free Wave Soldering System

Name: MWSI

Model:

Features:

Buffer conveyor: Linkage PCB loading mode with stainless steel chain
Conveyor system: equipped with stainless double hook finger(Model 4), alloy rail of preventing distortion design; Manual PCB width adjustment, conveying angle adjustable (4-7°), conveying speed controlled by frequency converter to adjust speed steplessly
Spray system: controlled by motor, Automatically adjust and digitally set



Series: Lead-Free Wave Soldering System

Name: PEAK-350

Model:

Features:

(1) WINXP Operation System, included Digital Reference Setting, Storage. Operation soft-ware available in English and Chinese version. Also, available in networking communication system.
(2) Using PC+PLC auto control system, IEC60204-1 standard for wiring system, flexible connection method, guaranty the wiring stability.



Series: Solder Paste Screen Printer Series

Name: GE (Genesis-Extended)

Model:

Features:

GE (Genesis-Extended) series screen printer, a "universal" screen printer updating from the mature and stable G3, have options of various modularization that fully meets demand of communication, medical treatment, auto electronics, military, computer and peripherals, consumer electronics, etc, becoming preferred product of highest performance price ratio within the industry.



Series: **other product Series**
Name: **AUTO PCB LOADER/UNLOADER**
Model: **ul-300**
Features:
PCB size:Min W50*L50-MaxW250*L330mm
- Conveying height:900±20mm
-Step range:10,20,30,40,50mm
-Loader size:W320*L350*H570mm
-Loading capacity:3
-Power supply: AC 220V 240W



Series: **other product Series**
Name: **AUTO PCB LOADER/UNLOADER LD-300**
Model:
Features:



Series: **other product Series**
Name: **Vacuum loader**
Model: **VLD-300**
Features:
PLC control
- Adsorbing position adjustable
- Production cycle: Min. 10S
- Dimension:L490*W760*H1100mm
- Conveying height:900±20mm
- Power supply: AC 220V 1φ 50HZ 200W

Semiconductor Packaging Equipme



Series: Semiconductor Packaging Equipme

Name: TH307

Model:

Features:

The drastic fluctuations in semiconductor industry are astonishing. NAND flash memory stood out conspicuously during he period of 2005-2007, the shipment boosted up, and manufacturers successively invested in NAND field. The emerging DDR2 was once promoted greatly by Microsoft Vista. In wafer OEM,a fierce competition on advanced manufacturing process is under way, and the manufacturers all have



Series: Semiconductor Packaging Equipme

Name: KAIJO

Model:

Features:

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Series: Semiconductor Packaging Equipme

Name: P309

Model:

Features:

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